TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20261119000.1**	**PCN Issued**	November 19, 2026
Qualification of LFAB as an additional Wafer Fab site, TIEMA as an additional assembly site and Design change for select devices		**Sample request deadline:**	January 18, 2027
		Estimated 1st ship date:	February 17, 2027
Sample requests received after** January 18, 2027 will not be supported.**			

Change type(s)
Packing/Shipping/Labeling Wafer Fab Site Assembly Site Design

PCN Details

Description of Change:

Texas Instruments is pleased to announce the addition of LFAB as an additional Wafer Fab site and TIEMA as an additional assembly site for the products listed in the "Product Affected" section.

Current Fab Site			**Additional Fab Site**		
Current Fab Site	**Process Technology**	**Wafer Diameter**	**Additional Fab site**	**Process Technology**	**Wafer Diameter**
UMC	F65	300mm	**LFAB**	F65	300mm

	Current Site	**Additional Site**
Assembly Site	CDAT	TIEMA

Qual details are provided in the Qual Data Section.

Reason for Change:	Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability:	• These devices include new die with schematic or behavior changes. • Request the Supporting Data Packet for more details on the changes.
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	**REACH**	**Green Status**	**IEC 62474**
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Fab Site Information

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
UMC	UMI	SGP	SUNNYVALE
LFAB	**LHI**	**USA**	**Lehi**

Die Rev:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
C	**D**

Assembly Site Information

Assembly Site	Assembly Site Origin Code (22L)	Assembly Site Country Code (23L)	Assembly Site City
CDAT	CDA	CHN	Chengdu
TIEMA	CU6	MYS	MELAKA

Sample product shipping label (not actual product label):



Products Affected

CC1314R106T0RGZR	CC1354P106T0RGZR	CC2674R106T0RGZR	CC1354R106T0RGZR
CC2653P104T0RGZR	CC2674P106T0RGZR		

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1354P106T0RSKR	Qual Device: CC1314R106T0RSKR	Qual Device: CC1354P106T0RGZR	Qual Device: CC2674R106T0RGZR	QBS Reference: CC2642R1TWRGZRQ1
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	3/231/0	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	1000 Cycles	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	3/231/0	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	500 Hours	-	-	-	-	3/135/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	3/231/0
EDR	B3	NVM Data Retention*	150C, W/E Cycle Preconditioning	1000 Hours	-	-	3/231/0	-	3/231/0
ESD	E2	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	-	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	1/3/0	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	1/3/0	1/3/0	-	1/3/0	1/6/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	3/90/0	-	3/90/0

- QBS: Qual By Similarity, also known as Generic Data

- Qual Device CC1354P106T0RGZR is qualified at MSL3 260C
- Qual Device CC1354P106T0RSKR is qualified at MSL3 260C
- Qual Device CC1314R106T0RSKR is qualified at MSL3 260C
- Qual Device CC2674R106T0RGZR is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- The qualification conditions stated in the table above apply to the qual device. The QBS references have either the same conditions or JEDEC-standard equivalent conditions.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2409-019

CC13XXX106T0RZGR Family
Approve Date 18-November-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: CC1314R106T0RSKR	Qual Device: CC1354P106T0RGZR	Qual Device: CC1354P106T0RSKR	Qual Device: CC2674R106T0RGZR	QBS Process Reference: CC2642R1FRGZR	QBS Package Reference: MSPM0G3507SRGZR	QBS Package Reference: LM26LVQISD-130/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	-	1/77/0	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	3/231/0	3/231/0
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	-	-
EDR	B3	NVM Data Retention	150C, W/E Cycle Preconditioning	1000 Hours	-	-	-	-	3/231/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	1/22/0	-
ESD	E2	ESD CDM	-	500 Volts	1/3/0	-	1/3/0	-	1/3/0	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/3/0	-	1/3/0	1/3/0	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	1/3/0	1/3/0	1/6/0	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	1/30/0	-	-	3/90/0	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device CC1314R106T0RSKR is qualified at MSL3 260C
- Qual Device CC1354P106T0RGZR is qualified at MSL3 260C
- Qual Device CC1354P106T0RSKR is qualified at MSL3 260C
- Qual Device CC2674R106T0RGZR is qualified at MSL3 260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
- The qualification conditions stated in the table above apply to the qual device. The QBS references have either the same conditions or JEDEC-standard equivalent conditions.

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2603-030

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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